

ABSTRACT OF THE DISCLOSURE

To clean contaminants on a substrate including a metal wiring formed thereon, a cleaning solution including diluted aqueous sulfuric acid solution is applied onto the substrate. Mega-sonic energy is applied to the cleaning solution on the substrate. The contaminants are removed from the substrate in accordance with the reaction between the diluted aqueous sulfuric acid solution and the contaminant while the mega-sonic energy is applied to the substrate. The corrosion of the metal wiring is prevented because of the cleaning solution including the diluted aqueous sulfuric acid solution. Additionally, the damage of the substrate is reduced because the mega-sonic energy is appropriately applied to the substrate.

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